SCLS140D – DECEMBER 1982 – REVISED AUGUST 2003

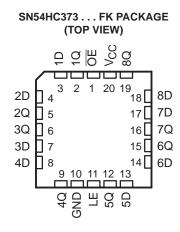
- Wide Operating Voltage Range of 2 V to 6 V
- High-Current 3-State True Outputs Can Drive Up To 15 LSTTL Loads
- Low Power Consumption, 80-μA Max I_{CC}
- Typical t_{pd} = 13 ns



	_				
OE	ď	1	U	20] v _{cc}
1Q	d	2		19] 8Q
1D	þ	3		18] 8D
2D	D.	4		17]7D
2Q	D	5		16] 7Q
3Q	D	6		15] 6Q
3D	D	7		14] 6D
4D	D	8		13] 5D
4Q	þ	9		12] 5Q
GND	q	10		11	LE



- Low Input Current of 1 μA Max
- Eight High-Current Latches in a Single Package
- Full Parallel Access for Loading



description/ordering information

These 8-bit latches feature 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. They are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

The eight latches of the 'HC373 devices are transparent D-type latches. While the latch-enable (LE) input is high, the Q outputs follow the data (D) inputs. When LE is taken low, the Q outputs are latched at the levels that were set up at the D inputs.

TA	PACKA	3E†	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – N	Tube of 20	SN74HC373N	SN74HC373N
		Tube of 25	SN74HC373DW	110070
	SOIC – DW	Reel of 2000	SN74HC373DWR	HC373
4000 to 0500	SOP – NS	Reel of 2000	SN74HC373NSR	HC373
–40°C to 85°C	SSOP – DB	Reel of 2000	SN74HC373DBR	HC373
		Tube of 70	SN74HC373PW	
	TSSOP – PW	Reel of 2000	SN74HC373PWR	HC373
		Reel of 250	SN74HC373PWT	
	CDIP – J	Tube of 20	SNJ54HC373J	SNJ54HC373J
–55°C to 125°C	CFP – W	Tube of 85	SNJ54HC373W	SNJ54HC373W
	LCCC – FK	Tube of 55	SNJ54HC373FK	SNJ54HC373FK

ORDERING INFORMATION

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



Copyright © 2003, Texas Instruments Incorporated On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

SCLS140D - DECEMBER 1982 - REVISED AUGUST 2003

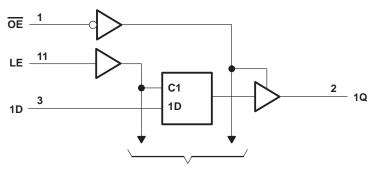
description/ordering information (continued)

An output-enable (OE) input places the eight outputs in either a normal logic state (high or low logic levels) or the high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without interface or pullup components.

OE does not affect the internal operations of the latches. Old data can be retained or new data can be entered while the outputs are off.

		ION TAI	
	INPUTS	OUTPUT	
OE	LE	D	Q
L	Н	Н	Н
L	Н	L	L
L	L	Х	Q ₀
Н	Х	Х	z

logic diagram (positive logic)



To Seven Other Channels

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) (see Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$) Continuous output current, I_O ($V_O = 0$ to V_{CC}). Continuous current through V_{CC} or GND Package thermal impedance, θ_{JA} (see Note 2): I	-0.5 e Note 1)) (see Note 1) DB package DW package N package	±20 mA ±20 mA ±35 mA ±70 mA 70°C/W 58°C/W 69°C/W
1	N package NS package PW package	60°C/W
	–65°C t	

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.



SCLS140D - DECEMBER 1982 - REVISED AUGUST 2003

recommended operating conditions (see Note 3)

			SN	154HC37	'3	SN	174HC37	3	
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage		2	5	6	2	5	6	V
		$V_{CC} = 2 V$	1.5			1.5			
VIH	High-level input voltage	$V_{CC} = 4.5 V$	3.15			3.15			V
		$V_{CC} = 6 V$	4.2			4.2			
		$V_{CC} = 2 V$			0.5			0.5	
VIL	Low-level input voltage	$V_{CC} = 4.5 V$			1.35			1.35	V
		ACC = 6 A			1.8			1.8	
VI	Input voltage		0		VCC	0		VCC	V
VO	Output voltage		0		VCC	0		VCC	V
		$V_{CC} = 2 V$			1000			1000	
$\Delta t / \Delta v$	Input transition rise/fall time	$V_{CC} = 4.5 V$			500			500	ns
		VCC = 6 V			400			400	
ТА	Operating free-air temperature		-55		125	-40		85	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

				Т	A = 25°C	;	SN54H	IC373	SN74H	C373	
PARAMETER	TEST CO	ONDITIONS	VCC	MIN	TYP	MAX	MIN	MAX	MIN MAX		UNIT
			2 V	1.9	1.998		1.9		1.9		
		I _{OH} = -20 μA	4.5 V	4.4	4.499		4.4		4.4		
VOH	$V_I = V_{IH} \text{ or } V_{IL}$		6 V	5.9	5.999		5.9		5.9		V
		$I_{OH} = -6 \text{ mA}$	4.5 V	3.98	4.3		3.7		3.84		
		I _{OH} = -7.8 mA	6 V	5.48	5.8		5.2		5.34		
			2 V		0.002	0.1		0.1		0.1	
		l _{OL} = 20 μA	4.5 V		0.001	0.1		0.1		0.1	
V _{OL}	$V_{I} = V_{IH} \text{ or } V_{IL}$		6 V		0.001	0.1		0.1		0.1	V
		IOL = 6 mA	4.5 V		0.17	0.26		0.4		0.33	
		I _{OL} = 7.8 mA	6 V		0.15	0.26		0.4		0.33	
lı	$A^{I} = A^{CC} \text{ or } 0$		6 V		±0.1	±100		±1000		±1000	nA
I _{OZ}	AO = ACC or 0		6 V		±0.01	±0.5		±10		±5	μΑ
ICC	$V_I = V_{CC} \text{ or } 0,$	IO = 0	6 V			8		160		80	μΑ
Ci			2 V to 6 V		3	10		10		10	pF



SN54HC373, SN74HC373 OCTAL TRANSPARENT D-TYPE LATCHES WITH 3-STATE OUTPUTS SCLS140D - DECEMBER 1982 - REVISED AUGUST 2003

timing requirements over recommended operating free-air temperature range (unless otherwise noted)

			T _A = 2	25°C	SN54H	IC373	SN74H	C373	
		VCC	MIN	MAX	MIN	MAX	MIN	MAX	UNIT
		2 V	80		120		100		
tw	Pulse duration, LE high	4.5 V	16		24		20		ns
		6 V	14		20		17		
		2 V	50		75		63		
t _{su}	Setup time, data before LE \downarrow	4.5 V	10		15		13		ns
		6 V	9		13		11		
		2 V	20		26		24		
^t h	Hold time, data after LE \downarrow	4.5 V	10		13		12		ns
		6 V	10		13		12		

switching characteristics over recommended operating free-air temperature range, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

DADAMETED	FROM	то		Т	ן = 25°C	;	SN54H	IC373	SN74H	IC373																											
PARAMETER	(INPUT)	(OUTPUT)	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT																										
			2 V		58	150		225		190																											
	D	Q	4.5 V		15	30		45		38																											
			6 V		13	26		38		32																											
^t pd			2 V		73	175		265		220	ns																										
	LE	Any Q	4.5 V		18	35		53		44																											
			6 V		15	30		45		38																											
			2 V		65	150		225		190																											
ten	OE	Any Q	4.5 V		17	30		45		38	ns																										
			6 V		14	26		38		32																											
			2 V		50	150		225		190																											
^t dis	OE	Any Q	4.5 V		15	30		45		38	ns																										
			6 V		13	26		38		32																											
			2 V		28	60		90		75																											
tt		Any Q	Any Q	Any Q	Any Q	Any Q	Any Q	Any Q	Any Q	Any Q	Any Q	Any Q	Any Q	Any Q	Any Q	Any Q	Any Q	Any Q	Any Q	Any Q	Any Q	Any Q	Any Q	Any Q 🖉	Any Q	Any Q	Any Q	Any Q	4.5 V		8	12		18		15	ns
			6 V		6	10		15		13																											



SN54HC373, SN74HC373 **OCTAL TRANSPARENT D-TYPE LATCHES** WITH 3-STATE OUTPUTS SCLS140D – DECEMBER 1982 – REVISED AUGUST 2003

switching characteristics over recommended operating free-air temperature range, $C_L = 150 \text{ pF}$ (unless otherwise noted) (see Figure 1)

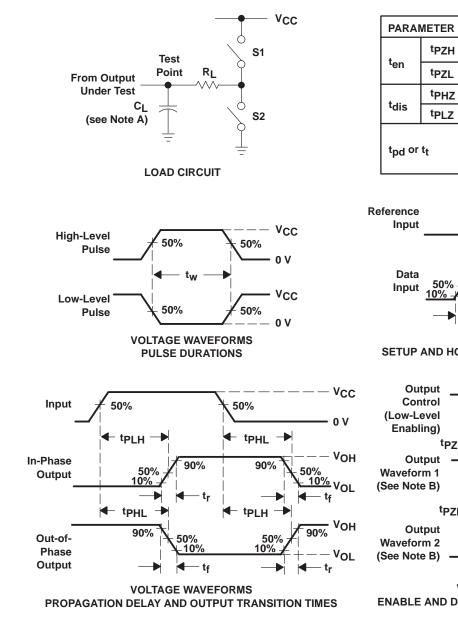
	FROM	то		Тд	λ = 25°C	;	SN54H	IC373	SN74H	IC373	
PARAMETER	(INPUT)	(OUTPUT)	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
			2 V		82	200		300		250	
	D	Q	4.5 V		22	40		60		50	
			6 V		19	34		51		43	
^t pd			2 V		100	225		335		285	ns
	LE	Any Q	4.5 V		24	45		67		57	
			6 V		20	38		57		48	
			2 V		90	200		300		250	
^t en	OE	Any Q	4.5 V		23	40		60		50	ns
			6 V		19	34		51		43	
			2 V		45	210		315		265	
t		Any Q	4.5 V		17	42		63		53	ns
			6 V		13	36		53		45	

operating characteristics, $T_A = 25^{\circ}C$

	PARAMETER	TEST CONDITIONS	TYP	UNIT
Cpd	Power dissipation capacitance per latch	No load	100	pF

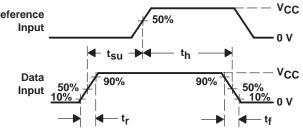


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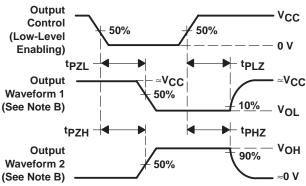


PARAMETER MEASUREMENT INFORMATION





VOLTAGE WAVEFORMS SETUP AND HOLD AND INPUT RISE AND FALL TIMES



VOLTAGE WAVEFORMS ENABLE AND DISABLE TIMES FOR 3-STATE OUTPUTS

- NOTES: A. CL includes probe and test-fixture capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 C. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following
 - characteristics: PRR \leq 1 MHz, Z_O = 50 Ω , t_f = 6 ns, t_f = 6 ns.
 - D. The outputs are measured one at a time with one input transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms





24-Aug-2018

PACKAGING INFORMATION

Orderable Device		Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
5962-8407201VRA	(1) ACTIVE	CDIP	J	20	1	(2) TBD	(6) A42	(3) N / A for Pkg Type	-55 to 125	(4/5) 5962-8407201VR	
5962-6407201VRA	ACTIVE	CDIP	J	20	I	IDU	A42	N/AIOIPKg Type	-55 10 125	5962-6407201VR A	Samples
										SNV54HC373J	
5962-8407201VSA	ACTIVE	CFP	W	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8407201VS	Samples
										A	Samples
0.40700.404						755			55 / 405	SNV54HC373W	
84072012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	84072012A SNJ54HC	Samples
										373FK	
8407201RA	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	8407201RA	Samala
										SNJ54HC373J	Samples
8407201SA	ACTIVE	CFP	W	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	8407201SA	Samples
										SNJ54HC373W	
JM38510/65403B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/	Samples
		0010				755			55 / 405	65403B2A	
JM38510/65403BRA	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 65403BRA	Samples
M38510/65403B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/	
W30310/03403D2A	AOTIVE	2000		20	1	100	TOOTTERTE		00 10 120	65403B2A	Samples
M38510/65403BRA	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/	S1
										65403BRA	Samples
SN54HC373J	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54HC373J	Samples
SN74HC373DBR	ACTIVE	SSOP	DB	20	2000	Green (RoHS	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC373	
3N/4003/3DDK	ACTIVE	330F	DB	20	2000	& no Sb/Br)	CU NIFDAU	Level-1-200C-UNLIM	-40 10 85	HU373	Samples
SN74HC373DW	ACTIVE	SOIC	DW	20	25	Green (RoHS	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC373	C 1
						& no Sb/Br)					Samples
SN74HC373DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC373	Samples
						& no Sb/Br)					Jampies
SN74HC373DWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC373	Samples
						& no Sb/Br)					
SN74HC373N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 85	SN74HC373N	Samples
			NI			()		N/ A fan Dian Trans	40 to 05		
SN74HC373NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 85	SN74HC373N	Samples



PACKAGE OPTION ADDENDUM

24-Aug-2018

Orderable Device	Status	Package Type	Package	Pins	Package	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
SN74HC373NSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC373	Samples
SN74HC373NSRE4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC373	Samples
SN74HC373PW	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC373	Samples
SN74HC373PWE4	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC373	Samples
SN74HC373PWR	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC373	Samples
SN74HC373PWRE4	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC373	Samples
SN74HC373PWT	ACTIVE	TSSOP	PW	20	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC373	Samples
SNJ54HC373FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	84072012A SNJ54HC 373FK	Samples
SNJ54HC373J	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	8407201RA SNJ54HC373J	Samples
SNJ54HC373W	ACTIVE	CFP	W	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	8407201SA SNJ54HC373W	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.



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24-Aug-2018

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN54HC373, SN54HC373-SP, SN74HC373 :

- Catalog: SN74HC373, SN54HC373
- Military: SN54HC373
- Space: SN54HC373-SP

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications
- Space Radiation tolerant, ceramic packaging and qualified for use in Space-based application

PACKAGE MATERIALS INFORMATION

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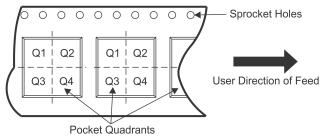
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TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74HC373DBR	SSOP	DB	20	2000	330.0	16.4	8.2	7.5	2.5	12.0	16.0	Q1
SN74HC373DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
SN74HC373NSR	SO	NS	20	2000	330.0	24.4	8.4	13.0	2.5	12.0	24.0	Q1
SN74HC373PWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.0	1.4	8.0	16.0	Q1
SN74HC373PWT	TSSOP	PW	20	250	330.0	16.4	6.95	7.0	1.4	8.0	16.0	Q1

TEXAS INSTRUMENTS

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PACKAGE MATERIALS INFORMATION

2-Oct-2019



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74HC373DBR	SSOP	DB	20	2000	367.0	367.0	38.0
SN74HC373DWR	SOIC	DW	20	2000	367.0	367.0	45.0
SN74HC373NSR	SO	NS	20	2000	367.0	367.0	45.0
SN74HC373PWR	TSSOP	PW	20	2000	367.0	367.0	38.0
SN74HC373PWT	TSSOP	PW	20	250	367.0	367.0	38.0

LEADLESS CERAMIC CHIP CARRIER

FK (S-CQCC-N**) 28 TERMINAL SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004



DB0020A



PACKAGE OUTLINE

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M. 2. This drawing is subject to change without notice. 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
- 5. Reference JEDEC registration MO-150.



DB0020A

EXAMPLE BOARD LAYOUT

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



DB0020A

EXAMPLE STENCIL DESIGN

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



MECHANICAL DATA

PLASTIC SMALL-OUTLINE PACKAGE

0,51 0,35 ⊕0,25⊛ 1,27 8 14 0,15 NOM 5,60 8,20 5,00 7,40 \bigcirc Gage Plane ₽ 0,25 7 1 1,05 0,55 0-10 Δ 0,15 0,05 Seating Plane — 2,00 MAX 0,10PINS ** 14 16 20 24 DIM 10,50 10,50 12,90 15,30 A MAX A MIN 9,90 9,90 12,30 14,70 4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.

NS (R-PDSO-G**)

14-PINS SHOWN

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



J (R-GDIP-T**) 14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

PW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



NOTES:

A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994. β . This drawing is subject to change without notice.

Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.

Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.

E. Falls within JEDEC MO-153



LAND PATTERN DATA



NOTES: Α. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
 C. Publication IPC-7351 is recommended for alternate design.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- \triangle The 20 pin end lead shoulder width is a vendor option, either half or full width.



DW0020A



PACKAGE OUTLINE

SOIC - 2.65 mm max height

SOIC



NOTES:

- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M. 2. This drawing is subject to change without notice. 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
- 5. Reference JEDEC registration MS-013.



DW0020A

EXAMPLE BOARD LAYOUT

SOIC - 2.65 mm max height

SOIC



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



DW0020A

EXAMPLE STENCIL DESIGN

SOIC - 2.65 mm max height

SOIC



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



W (R-GDFP-F20)

CERAMIC DUAL FLATPACK



- NOTES: A. All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice. В.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 D. Index point is provided on cap for terminal identification only.
 E. Falls within Mil-Std 1835 GDFP2-F20



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